

Abstract

Provided are an epoxy resin which is excellent in low viscosity and handling property as a solid, is excellent in heat resistance, moisture resistance, and thermal conductivity as well, and is useful for applications such as lamination, molding, casting, and adhesion, an epoxy resin composition using the resin, and a cured product of the composition. The epoxy resin is represented by the following general formula (1), exhibits an endothermic peak temperature ranging from 100 to 150°C based on a melting point in differential scanning calorimetry, and is crystalline. Further, the epoxy resin composition includes as essential components the epoxy resin and a curing agent. In the general formula (1), n represents 0.2 to 4.0 as an average, and G represents a glycidyl group.